

# Kazuhiro Ito

## List of Publications by Year in descending order

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62  
papers

532  
citations

759233

12  
h-index

677142

22  
g-index

62  
all docs

62  
docs citations

62  
times ranked

425  
citing authors

#	ARTICLE	IF	CITATIONS
1	Formation of Ti diffusion barrier layers in Thin Cu(Ti) alloy films. Journal of Electronic Materials, 2005, 34, 592-599.	2.2	78
2	Ohmic contacts on silicon carbide: The first monolayer and its electronic effect. Physical Review B, 2009, 80, .	3.2	63
3	Benefits of intermediate-layer formation at the interface of Nb/Cu and Ta/Cu explosive clads. Materials and Design, 2019, 166, 107610.	7.0	48
4	Simultaneous formation of p- and n-type ohmic contacts to 4H-SiC using the ternary Ni/Ti/Al system. Journal of Electronic Materials, 2005, 34, 1310-1312.	2.2	35
5	Growth and Microstructure of Epitaxial Ti<sub>3</sub>SiC<sub>2</sub> Contact Layers on SiC. Materials Transactions, 2009, 50, 1071-1075.	1.2	30
6	Characterization of Self-Formed Ti-Rich Interface Layers in Cu(Ti)/Low-k Samples. Journal of Electronic Materials, 2008, 37, 1148-1157.	2.2	29
7	Oxidation protective silicide coating on Mo-Si-B alloys. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2005, 36, 627-636.	2.2	25
8	Simultaneous Formation of Ni/Al Ohmic Contacts to Both n- and p-Type 4H-SiC. Journal of Electronic Materials, 2008, 37, 1674-1680.	2.2	21
9	Effects of Al ion implantation to 4H-SiC on the specific contact resistance of TiAl-based contact materials. Science and Technology of Advanced Materials, 2006, 7, 496-501.	6.1	18
10	Rutherford Backscattering Spectrometry Analysis of Self-Formed Ti-Rich Interface Layer Growth in Cu(Ti)/Low-k Samples. Journal of Electronic Materials, 2009, 38, 1913-1920.	2.2	17
11	Visualizing the vibration effect on the tandem-pulsed gas metal arc welding in the presence of surface tension active elements. International Journal of Heat and Mass Transfer, 2020, 161, 120310.	4.8	14
12	Grain Growth Mechanism of Cu Thin Films. Materials Transactions, 2005, 46, 1737-1740.	1.2	13
13	Phase transitions from semiconductive amorphous to conductive polycrystalline in indium silicon oxide thin films. Applied Physics Letters, 2016, 109, .	3.3	13
14	The effect of Nb and W alloying additions to the thermal expansion anisotropy and elastic properties of Mo <sub>5</sub> Si <sub>3</sub> . Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2005, 36, 533-538.	2.2	12
15	Epitaxial growth of GaN layers on metallic TiN buffer layers. Journal of Electronic Materials, 2006, 35, 1806-1811.	2.2	12
16	Dissimilar materials joining between stainless steel and carbon fiber reinforced thermoplastic by friction lap joining. Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society, 2017, 35, 29-35.	0.5	11
17	Metallurgical Characterization of Penetration Shape Change in Workpiece Vibration-Assisted Tandem-Pulsed Gas Metal Arc Welding. Materials, 2020, 13, 3096.	2.9	10
18	Growth of GaN on Nitriding TiN Buffer Layers. Materials Transactions, 2005, 46, 1975-1978.	1.2	9

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19	Resistivity Reduction and Adhesion Increase Induced by Surface and Interface Segregation of Ti Atoms in Cu(Ti) Alloy Films on Glass Substrates. <i>Materials Transactions</i> , 2010, 51, 1627-1632.	1.2	8
20	Ti-Rich Barrier Layers Self-Formed on Porous Low-k Layers Using Cu(1Åat.%ÅTi) Alloy Films. <i>Journal of Electronic Materials</i> , 2010, 39, 1326-1333.	2.2	6
21	Effects of Dielectric-Layer Composition on Growth of Self-Formed Ti-Rich Barrier Layers in Cu(1) Tj ETQq1 1 0.784314 rgBT /Overlock	1.2	5
22	Low-Temperature Synthesis of High-Adhesion Cu(Mg) Alloy Films on Glass Substrates. <i>Journal of Electronic Materials</i> , 2014, 43, 2540-2547.	2.2	5
23	Effects of Insert Metal Type on Interfacial Microstructure During Dissimilar Joining of TiAl Alloy to SCM440 by Friction Welding. <i>Metals and Materials International</i> , 2018, 24, 626-632.	3.4	5
24	Cladding of a crack-free W plate on Cu plates using explosive welding at higher collision velocity with lower collision angle. <i>Results in Materials</i> , 2020, 5, 100023.	1.8	5
25	Effects of TiN Buffer Layer Thickness on GaN Growth. <i>Journal of Electronic Materials</i> , 2009, 38, 511-517.	2.2	4
26	Surface Microstructure Modifications of Low Carbon Steel Welds Produced by Low-Heat-Input Friction Stir Processing. <i>Materials Transactions</i> , 2020, 61, 1613-1619.	1.2	4
27	Study on the Microstructure and Liquid Phase Formation in a Semisolid Gray Cast Iron. <i>Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science</i> , 2017, 48, 2293-2303.	2.1	3
28	Predicting Tensile Properties of Friction-Stir-Welded 6063 Aluminum with Experimentally Measured Welding Heat Input. <i>Acta Metallurgica Sinica (English Letters)</i> , 2020, 33, 1235-1242.	2.9	3
29	Application of Friction Stir Processing to Weld Toe for Fatigue Strength Improvement of High-Strength Low-Alloy Steel Joint. <i>Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society</i> , 2018, 36, 1WL-4WL.	0.5	3
30	Low Thermal Conductivity and Related Thermoelectric Properties of Zn4Sb3 and CoSb3 Thin Films. <i>Materials Research Society Symposia Proceedings</i> , 2003, 793, 188.	0.1	2
31	Growth of Ti-Based Interface Layer in Cu(Ti)/Glass Samples. <i>Materials Transactions</i> , 2011, 52, 491-497.	1.2	2
32	Evaluation of Hydrogen-induced Cracking Behavior in Duplex Stainless Steel by Numerical Simulation of Stress and Diffusible Hydrogen Distribution at the Microstructural Scale. <i>Tetsu-To-Hagane/Journal of the Iron and Steel Institute of Japan</i> , 2020, 106, 214-223.	0.4	2
33	Characterization of Shock Wave Damages in Explosion Welded Mo/Cu Clads. <i>Metals</i> , 2021, 11, 501.	2.3	2
34	Evaluation of Hydrogen-induced Cracking Behavior in Duplex Stainless Steel by Numerical Simulation of Stress and Diffusible Hydrogen Distribution at the Microstructural Scale. <i>ISIJ International</i> , 2021, 61, 1135-1142.	1.4	2
35	Numerical Simulation on Effect of Microstructure on Hydrogen-induced Cracking Behavior in Duplex Stainless Steel Weld Metal. <i>ISIJ International</i> , 2021, 61, 1236-1244.	1.4	2
36	A unique CEL numerical method on material flow in a molten pool of workpiece vibration assisted welding. <i>Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society</i> , 2020, 38, 54s-58s.	0.5	2

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37	Plastic deformation of single crystals with the C11b structure : Effect of the c/a axial ratio. Materials Research Society Symposia Proceedings, 2000, 646, 62.	0.1	1
38	Epitaxial GaN Layer Growth Using Nitrogen Enriched TiN Buffer Layers. Materials Research Society Symposia Proceedings, 2006, 916, 6.	0.1	1
39	Simultaneous Formation of Ohmic Contacts for Both N- and P-Type 4H-Sic Using Nial-Based Contact Materials. Materials Research Society Symposia Proceedings, 2006, 911, 5.	0.1	1
40	Characterization of self-formed Ti-based barrier layers in Cu(Ti)/dielectric-layer samples using X-ray Photoelectron Spectroscopy. , 2010, , .		1
41	Numerical Simulation on Effect of Microstructure on Hydrogen-induced Cracking Behavior in Duplex Stainless Steel Weld Metal. Tetsu-To-Hagane/Journal of the Iron and Steel Institute of Japan, 2020, 106, 224-234.	0.4	1
42	Effects of Microstructural Modification by Friction Stir Processing on Fracture Toughness of Low-carbon Steel Welds. Journal of Smart Processing, 2019, 8, 29-35.	0.1	1
43	Friction stir welding of ultra high-purity aluminium thin sheets never to lower high conductivity at ultra-low temperature. Welding International, 2020, 34, 125-137.	0.7	1
44	Microstructure and Impact Toughness Relationship for Different Nickel Level of Electrode in Multi-pass FCA Welded SM570-TMC Steel Joint. Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society, 2020, 38, 154s-158s.	0.5	1
45	Microstructure features and formation mechanism in a newly developed electroslag welding. Welding in the World, Le Soudage Dans Le Monde, 0, , 1.	2.5	1
46	Physical and Mechanical Properties of Mo <sub>5</sub> X <sub>3</sub> +1± (X=Si, B, C) Single Crystals. Materials Research Society Symposia Proceedings, 2002, 753, 1.	0.1	0
47	On Mo-9Si-18B Alloys with T2-Moss eutectic microstructure: Mechanical Properties and Protective Silicide Coating. Materials Research Society Symposia Proceedings, 2002, 753, 1.	0.1	0
48	Reversible Hydrogen Absorption/Desorption and Related Lattice Deformation of Ti <sub>3</sub> Al Based Alloys in the Ti-Al-Nb System. Materials Research Society Symposia Proceedings, 2002, 753, 1.	0.1	0
49	Simultaneous Formation of n- and p-Type Ohmic Contacts to 4H-SiC Using the Binary Ni/Al System. Materials Research Society Symposia Proceedings, 2008, 1069, 1.	0.1	0
50	Self-formation of Ti-rich Layers at Cu(Ti)/low-k Interfaces. Materials Research Society Symposia Proceedings, 2008, 1079, 1.	0.1	0
51	Self-Formed Ti-Rich Barrier Layers in Cu(Ti)•Low-k Samples. , 2009, , .		0
52	Rutherford Backscattering Spectrometry Analysis of Growth Rate and Activation Energy for Self-formed Ti-rich Interface Layers in Cu(Ti)/Low-k Samples. Materials Research Society Symposia Proceedings, 2009, 1156, 1.	0.1	0
53	Growth analysis of self-formed Ti-rich interface layers in Cu(Ti)/dielectric-layer samples using Rutherford Backscattering Spectrometry. , 2009, , .		0
54	Effects of heat-affected-zone microstructure and molten-zinc temperature on zinc embrittlement cracking induced. Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society, 2018, 36, 230-237.	0.5	0

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55	Interfacial Microstructures of TiAl-Based Ohmic Contacts to p-Type SiC Semiconductor. <i>Materia Japan</i> , 2004, 43, 992-992.	0.1	0
56	OS15-1-1 Damage Evaluation and Life Assessment of Heat-Resisting Steels and Alloys by Using Positron Annihilation. The Abstracts of ATEM International Conference on Advanced Technology in Experimental Mechanics Asian Conference on Experimental Mechanics, 2011, 2011.10, _OS15-1-1-.	0.0	0
57	Report of Visual-JW 2016. <i>Yosetsu Gakkai Shi/Journal of the Japan Welding Society</i> , 2017, 86, 189-191.	0.1	0
58	TEM Characterization of Explosive Cladding Interfaces between Refractory Metal (group V or VI) and Cu Plates. <i>Journal of Smart Processing</i> , 2019, 8, 261-266.	0.1	0
59	Study on Residual Stress by Neutron Diffraction in SM570-TMC Welded by Flux-Cored Wires Containing Different Nickel. <i>Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society</i> , 2020, 38, 116s-120s.	0.5	0
60	Friction stir welding of ultrahigh-purity aluminum thin sheets never to lower high conductivity at ultra-low temperature. <i>Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society</i> , 2020, 38, 253-262.	0.5	0
61	Fatigue strength improvement due to alloying steel weld toes with WC tool constituent elements through friction stir processing. <i>International Journal of Advanced Manufacturing Technology</i> , 2022, 119, 6203-6213.	3.0	0
62	Study on Effect of Microstructure on Hydrogen Cracking in Duplex Stainless Steel Welds. The Proceedings of the Materials and Mechanics Conference, 2021, 2021, OS1601.	0.0	0